### IFIC – SiWECAL activities: gluing and more

César Blanch, <u>Adrián Irles</u>

\*AITANA group at IFIC – CSIC/UV



#### **Hot-topics**



#### Dellamination issues of CALICE.

Origin

- Aging of glue ? (radiation doesn't seem to be an issue, after comparing boards)
- Procedure of the gluing. Process managed by Jussieu, subject to the expertise availability and production of only small batches with large separation in time.
- PCB deformation → its planarity is assured during gluing with aspiration means ... once it is released, the full mechanic stress is on the glue dots.

#### Material budget

- Goal is to have glue dots of 50um for ECAL-p
  - In CALICE we have 100-150um
  - .... but we have never really cared about the thickness.





## **Part 1: PCB deformations**

#### Tools at IFIC



- FEV 12 naked
  - Not the same that we used for the glue tests.
- Climatic chamber
- Tool for z-axis characterization via optical focus
  - Mitutyo Quick Vision Accel, Modelo 808
  - https://www.mitutoyo.com/webfoo/wp-content/uploa ds/2118\_Quick\_Vision.pdf
- Several 12-24h cycles with 80-100 degrees, 10-80% humidity









#### results



- Basically no extra deformation observed after the cycles
  - But an initial +120um, -200um deformation from the middle plane
- Curing at 100degrees may not be an issue at all.
  - Tests done without sensors/components! → ATTENTION... first tests with fake wafer show opposite results (August 2023)
- ▶ Would this PCB have been used for gluing sensors?
  - The aspiration plate was capable of support it removing the deformation....
- ▶ However, the component soldering is done in more extreme conditions
  - 200-250 degrees with very quick peaks of temperature. Studies to be done...



#### **New PCB generation**

- In production. Few samples per lab.
  - IFIC has one (fully equipped and functional...)
  - Not tested at IFIC yet

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- Metrology at IFIC doesn't show great results...
  - to be compared with metrologies before and after component soldering









# **Part 2: resistivity evolution**

#### **Resistivity of conductive epoxy**



- Several issues of sensor dellamination have been reported by SiW-ECAL
- Main suspects are the limited mechanical strength of the glue and the initial deformation of the PCBs
- However, we should not discard all other reasons
  - Conductive epoxys (silver balls) and aluminium can suffer oxydation, degrading the resistivity.



4.9 Ag ICA contact resistance changes at 85/85: (a) on Cu contacts, (b) on Au contacts, with (c) corresponding bulk resistivity variations.



#### Dummy tests using a flex pcb (FCAL)









First tests, beginning 2023



#### August 2023











#### August 2023











- New tests done in August 2023, using serynge with different glues (H20E, EJ4110)
- Measurement of resistivity being performed
- Different humidity storage conditions.
  - The lab (25degrees, ~20humidity) &

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• the workshop in my house - Palomar - (30 degrees... ~70-80% humidity)



### August 2023









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#### Results





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	E4110	E4	110-Lab	E4110-Palomar	H20E	H20E-Lab	H20E-Palomar
Bad (th>0.5)		32%	30%	30%	6 4%	9%	0%
Bad (th>1)		16%	6%	25%	6 0%	0%	0%

th=(R2/R1-1)







# **Part 3: gluing for tests**

### Glue

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• New equipment!



- Sandwich-maker style
- Two aspiration plates
  - One for the wafers
  - One for the PCBs (with components in it)
- Alignment in x-y done by the aspirations themselves and pivot tools
- Alignment in z done with micrometric screws
  - To deal with the PCB thickness tolerances (of possible hundreds of um)



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Also thermal curing using resistance and APDs for temperature control





#### Fake wafers -xy alignment







Alignment of fake transparent sensors

• 500um

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#### PCB -xy alignment



Alignment of the PCB

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- Design of the plates optimized to FEV2 & tolerances → the FEV12 seems to be slightly larger. The PCB has been machined to fit in the plate
- PCB without components





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#### **PCB -xy alignment**







#### **Z-alignment**







Tuneable for each use, using precision 3 micrometric screws together with feeler gauges

Z-alignment performed at 150um (separation between wafer and the pcb)





#### **Glue repartition**





#### Stencil

- 500um copper plate
- Holes of 0.8 or 1.2 mm diameter
- Stencil is a nice solution to keep the developments ongoing. Easy approach for tests.





#### **Glue repartition**







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curing





- ▶ 4 resistors (2 per aspiration plate)
- ▶ 80 degrees during 12h
  - + full weekend at room temp



#### results



- Very first test with only one fake wafer
  - We later completed the PCB with 3 more fake wafers
- The z-alignment seems improvable
  → more amount of glue per dot needed
  - A new test is done with 1.2mm diameter holes instead
  - This is to be better defined with the gluing robot and dosification system
- Some glue spread around PCB holes (due to the aspiration)







#### August 2023 – two PCBs shipped to IJCLab FIC A







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#### August 2023 – two PCBs shipped to IJCLab FIC 🔊

- Curing at 80 degrees for half a day (15h)
- Full procedure in the aspiration plate
- Deformation of the PCB visible after the process...
  - Not seen when doing tests in climatic chamber without wafers / aluminum plate





#### **Available aspiration plates at IFIC**



- ▶ We have aspiration plates for large surface wafers (CALICE)
- ▶ We have aspiration plates for CALICE PCBs (newest generation)
- We have aspiration plates for small test wafers + flex pcbs





# Part 4: improving glue mechanical properties

#### Pull tests at IJCLab – with underfill



- Setp -1 : use old PCBs with fake wafers to prepare a setup (done)
- Step 0: receive newer PCBs glued at IFIC (done)
- Step 1: cut the PCB in 4
- Step 2: Add underfill glue → with a serynge, from the lateral, add a a glue that fills the full wafer surface
  - Reference:
- Step 3: pull tests
  - Super-Glue two tool to hold all the surface of the PCB and the surface of fake wafers
  - Pull until it breaks and measure the needed force
- Detailed reports on the procedure and results are to come.
- Can they do it also with small wafers?



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Different glues, curing times, processes.. to be studied systematically



#### **Pull tests at IJCLab – with double tape**



- Another approach is to use double tape
  - The thinner we found is 150um which is perfectly okay for CALICE









#### **Pull tests at IJCLab – with double tape**









## **Part 5: the robot**

#### Summary & next steps



- ▶ The basic design of the tools and the procedure has been validated
- Fine tunning needed to optimize the alignment
  - Close collaboration with mechanical engineering services at IFIC (César as liason).
- Stencil approach to be overruled by robot and volumetric dosification system
- Precifluid & POLY DISPENSING SYSTEMS
- $\blacktriangleright$  Robot tested and now it is back in a box  $\rightarrow$  for the works in the lab.







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#### Update, august 2023 – testing the Robot





Video -- during robot installation







## Part 6: next steps

#### Next steps



Installation of clean room, material, laboratory desks, etc

- Installation of the probe station → same as shown by Itamar at the main meeting. The driver card is to be produced in Spain (waiting for cost estimation by company). The probe card is produced by CERN. The mechanical support?... IFIC.
- re-Training in the robot usage
- Tests with short flex cables and fake wafers:
  - Different glues, curing times, optimize the plates and aspiration
  - Focus on z-alignment  $\rightarrow$  are the 50um reachable? Let's worry about x-y later...
- ▶ I would like to produce a full CALICE-PCB with double tape and 4x500um wafers.











- Flexible thickness without stiffener: 0.139 mm - thickness with stiffener is 0.271 mm







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#### **Tests to be done January-April 2023**

- We have purchased a set of dummy substrates with aluminum and gold bath (as the Hammatsu sensors)
  - Delivery in ~ January
- We have orderd the epoxys (still waiting for the note on the gold based).
  - Delivery in January-February
- Yan is designing a special kapton fanout to be glued to the dummy sensors and perform resitance measurements of the glue dots.
  - Using a precision ohmemetre to measure mOhms.
  - Production/delivery?March?
- We are getting trained in the use of a climatic chamber here at IFIC: the idea is to tests the different glues and surfaces after several humidity cycles and check the resistivity.

Also access to a x-ray machine for a "visual" inspection.



4.9 Ag ICA contact resistance changes at 85/85: (a) on Cu contacts,(b) on Au contacts, with (c) corresponding bulk resistivity variations.

Bibliography reference on epoxy+silver glues performance (attached to the agenda)



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#### Curing in a climatic chamber





Ugly result

- But good enough to give qualitative results
- The resistivity between specific pads is measured after several humidity/temperature cycles performed



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#### Curing in a climatic chamber



Follow the datasheet, minimal time is 80degrees 3h

• Very low humidity during the full process (10%)

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#### **Resistivity measurements**



We should look only at tendencies, not absolute values

The G12-Gref (horizontal lines in 100%) are the reference values





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#### **Resistivity measurements**

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1 Initial setting 2 Curing 80deg, 8% humi. 3 24h 80%, 30degrees 4 72h room 5 24h 80%, 30degrees 6 24h 80%, 30degrees 7 24h 80%, 30degrees 8 16h 80%, 30degrees 9 4h 80% an 80degrees 10 12 days holidays – room temp 11 45 days room temp



We should look only at tendencies, not absolute values

- ▶ The G12-Gref (horizontal lines in 100%) are the reference values
- Resistivity increase after each humidity cycle



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- Resistivity increase after each humidity cycle

Step 9: Resistivity decreased after a heat cycle (with high humidity) → re-curing?

• The minimal requirements in the datasheet should be seen as the very minimum Irles A.,

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#### Activity 1 – aspiration plates design







#### Activity 1 – aspiration plates design



Also thermal curing using resistance and APDs for temperature control





#### X-rays exploration





Before curing

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After all cycles

I don't appreciate any difference...



#### Follow up tests

- Last drops of EJ2189 glue.
- New stencil for only one quarter
  - 1.2mm holes instead of 0.8
- Z-alignment performed at 150um
- Warm-up from 25 to 80 degrees took 1h15min
  - After that time, we remove the zaxis limitations of 150um
  - The plates did not move

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